#### **Features**

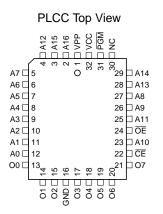
- Fast Read Access Time 90 ns
- Dual Voltage Range Operation
  - Unregulated Battery Power Supply Range, 2.7V to 3.6V or Standard 5V  $\pm$  10% Supply Range
- Compatible with JEDEC Standard AT27C010
- Low Power CMOS Operation
  - 20  $\mu$ A max. (less than 1  $\mu$ A typical) Standby for  $V_{CC}$  = 3.6V
  - 29 mW max. Active at 5 MHz for V<sub>CC</sub> = 3.6V
- JEDEC Standard Packages
  - 32-Lead PLCC
  - 32-Lead TSOP (8 x 20 mm)
  - 32-Lead VSOP (8 x 14 mm)
- High Reliability CMOS Technology
  - 2,000V ESD Protection
  - 200 mA Latchup Immunity
- Rapid™ Programming Algorithm 100 µs/byte (typical)
- CMOS and TTL Compatible Inputs and Outputs
  - JEDEC Standard for LVTTL and LVBO
- Integrated Product Identification Code
- Commercial and Industrial Temperature Ranges

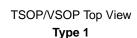
#### **Description**

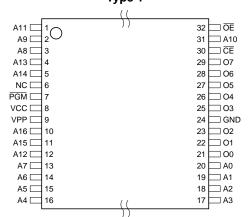
The AT27BV010 is a high performance, low power, low voltage 1,048,576-bit one-time programmable read only memory (OTP EPROM) organized as 128K by 8 bits. It requires only one supply in the range of 2.7V to 3.6V in normal read mode operation, making it ideal for fast, portable systems using either regulated or unregulated battery power. (continued)

## **Pin Configurations**

Pin Name	Function
A0 - A16	Addresses
O0 - O7	Outputs
CE	Chip Enable
ŌĒ	Output Enable
PGM	Program Strobe
NC	No Connect









1-Megabit (128K x 8) Unregulated Battery-Voltage<sup>™</sup> OTP EPROM

AT27BV010

Rev. 0344F-10/98





Atmel's innovative design techniques provide fast speeds that rival 5V parts while keeping the low power consumption of a 3V supply. At  $V_{CC}=2.7V,\,$  any byte can be accessed in less than 90 ns. With a typical power draw of only 18 mW at 5 MHz and  $V_{CC}=3V,\,$  the AT27BV010 consumes less than one fifth the power of a standard 5V EPROM. Standby mode supply current is typically less than 1  $\mu A$  at 3V. The AT27BV010 simplifies system design and stretches battery lifetime even further by eliminating the need for power supply regulation.

The AT27BV010 is available in industry standard JEDEC-approved one-time programmable (OTP) plastic PLCC, TSOP, and VSOP packages. All devices feature two-line control ( $\overline{\text{CE}}$ ,  $\overline{\text{OE}}$ ) to give designers the flexibility to prevent bus contention.

The AT27BV010 operating with V $_{CC}$  at 3.0V produces TTL level outputs that are compatible with standard TTL logic devices operating at V $_{CC}$  = 5.0V. At V $_{CC}$  = 2.7V, the part is compatible with JEDEC approved low voltage battery operation (LVBO) interface specifications. The device is also capable of standard 5-volt operation making it ideally suited for dual supply range systems or card products that are pluggable in both 3-volt and 5-volt hosts.

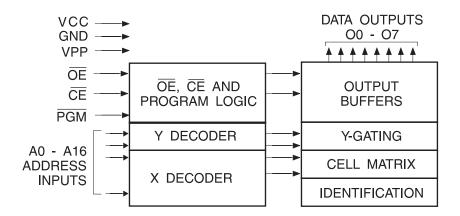
Atmel's AT27BV010 has additional features to ensure high quality and efficient production use. The Rapid™ Programming Algorithm reduces the time required to program the

part and guarantees reliable programming. Programming time is typically only 100  $\mu$ s/byte. The Integrated Product Identification Code electronically identifies the device and manufacturer. This feature is used by industry standard programming equipment to select the proper programming algorithms and voltages. The AT27BV010 programs exactly the same way as a standard 5V AT27C010 and uses the same programming equipment.

#### **System Considerations**

Switching between active and standby conditions via the Chip Enable pin may produce transient voltage excursions. Unless accommodated by the system design, these transients may exceed data sheet limits, resulting in device non-conformance. At a minimum, a 0.1  $\mu F$  high frequency, low inherent inductance, ceramic capacitor should be utilized for each device. This capacitor should be connected between the  $V_{CC}$  and Ground terminals of the device, as close to the device as possible. Additionally, to stabilize the supply voltage level on printed circuit boards with large EPROM arrays, a 4.7  $\mu F$  bulk electrolytic capacitor should be utilized, again connected between the  $V_{CC}$  and Ground terminals. This capacitor should be positioned as close as possible to the point where the power supply is connected to the array.

#### **Block Diagram**



#### **Absolute Maximum Ratings\***

Temperature Under Bias40°C to +85°C
Storage Temperature65°C to +125°C
Voltage on Any Pin with Respect to Ground2.0V to +7.0V <sup>(1)</sup>
Voltage on A9 with Respect to Ground2.0V to +14.0V <sup>(1)</sup>
V <sub>PP</sub> Supply Voltage with Respect to Ground2.0V to +14.0V <sup>(1)</sup>

\*NOTICE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability

Note:

Minimum voltage is -0.6V dc which may undershoot to -2.0V for pulses of less than 20 ns. Maximum output pin voltage is V<sub>CC</sub> + 0.75V dc which may be exceeded if certain precautions are observed (consult application notes) and which may overshoot to +7.0V for pulses of less than 20 ns.

#### **Operating Modes**

Mode \ Pin	CE	ŌĒ	PGM	Ai	V <sub>PP</sub>	V <sub>cc</sub>	Outputs
Read <sup>(2)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	X <sup>(1)</sup>	Ai	Х	V <sub>CC</sub> <sup>(2)</sup>	D <sub>OUT</sub>
Output Disable <sup>(2)</sup>	Х	V <sub>IH</sub>	Х	X	Х	V <sub>CC</sub> <sup>(2)</sup>	High Z
Standby <sup>(2)</sup>	V <sub>IH</sub>	X	Х	X	Х	V <sub>CC</sub> <sup>(2)</sup>	High Z
Rapid Program <sup>(3)</sup>	$V_{IL}$	V <sub>IH</sub>	V <sub>IL</sub>	Ai	V <sub>PP</sub>	V <sub>CC</sub> <sup>(3)</sup>	D <sub>IN</sub>
PGM Verify <sup>(3)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	V <sub>IH</sub>	Ai	V <sub>PP</sub>	V <sub>CC</sub> <sup>(3)</sup>	D <sub>OUT</sub>
PGM Inhibit <sup>(3)</sup>	V <sub>IH</sub>	X	X	X	V <sub>PP</sub>	V <sub>CC</sub> <sup>(3)</sup>	High Z
Product Identification <sup>(3)(5)</sup>	V <sub>IL</sub>	V <sub>IL</sub>	X	$A9 = V_H^{(4)}$ $A0 = V_{IH} \text{ or } V_{IL}$ $A1 - A16 = V_{IL}$	X	V <sub>CC</sub> <sup>(3)</sup>	Identification Code

- Notes: 1. X can be  $V_{IL}$  or  $V_{IH}$ .
  - 2. Read, output disable, and standby modes require, 2.7V  $\leq$  V  $_{CC} \leq$  3.6V, or 4.5V  $\leq$  V  $_{CC} \leq$  5.5V.
  - 3. Refer to Programming Characteristics. Programming modes require  $V_{CC}$  = 6.5V.
  - 4.  $V_H = 12.0 \pm 0.5 V$ .
  - 5. Two identifier bytes may be selected. All Ai inputs are held low (V<sub>IL</sub>), except A9 which is set to V<sub>H</sub> and A0 which is toggled low  $(V_{IL})$  to select the Manufacturer's Identification byte and high  $(V_{IH})$  to select the Device Code byte.





## **DC and AC Operating Conditions for Read Operation**

		AT27BV010-90	AT27BV010-12	AT27BV010-15
Operating Temperature	Com.	0°C - 70°C	0°C - 70°C	0°C - 70°C
(Case)	Ind.	-40°C - 85°C	-40°C - 85°C	-40°C - 85°C
V <sub>CC</sub> Power Supply		2.7V to 3.6V	2.7V to 3.6V	2.7V to 3.6V
		5V ± 10%	5V ± 10%	5V ± 10%

## **DC and Operating Characteristics for Read Operation**

Symbol	Parameter	Condition	Min	Max	Units
V <sub>CC</sub> = 2.7\	' to 3.6V				
I <sub>LI</sub>	Input Load Current	V <sub>IN</sub> = 0V to V <sub>CC</sub>		±1	μΑ
I <sub>LO</sub>	Output Leakage Current	V <sub>OUT</sub> = 0V to V <sub>CC</sub>		±5	μΑ
I <sub>PP1</sub> <sup>(2)</sup>	V <sub>PP</sub> <sup>(1)</sup> Read/Standby Current	$V_{PP} = V_{CC}$		10	μΑ
	V (1) Chan allow Command	$I_{SB1}$ (CMOS), $\overline{CE} = V_{CC\pm} 0.3V$		20	μΑ
I <sub>SB</sub>	V <sub>CC</sub> <sup>(1)</sup> Standby Current	$I_{SB2}$ (TTL), $\overline{CE} = 2.0$ to $V_{CC} + 0.5V$		100	μΑ
I <sub>cc</sub>	V <sub>CC</sub> Active Current	$f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}, V_{CC} = 3.6 \text{V}$		8	mA
	Innut I am Valta an	V <sub>CC</sub> = 3.0 to 3.6V	-0.6	0.8	V
$V_{IL}$	Input Low Voltage	V <sub>CC</sub> = 2.7 to 3.6V	-0.6	0.2 x V <sub>CC</sub>	V
	Local I Pale Mallana	V <sub>CC</sub> = 3.0 to 3.6V	2.0	V <sub>CC</sub> + 0.5	V
$V_{IH}$	Input High Voltage	V <sub>CC</sub> = 2.7 to 3.6V	0.7 x V <sub>CC</sub>	V <sub>CC</sub> + 0.5	V
	Output Low Voltage	I <sub>OL</sub> = 2.0 mA		0.4	V
V <sub>OL</sub>		I <sub>OL</sub> = 100 μA		0.2	V
		I <sub>OL</sub> = 20 μA		0.1	V
		I <sub>OH</sub> = -2.0 mA	2.4		V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -100 μA	V <sub>CC</sub> - 0.2		V
		I <sub>OH</sub> = -20 μA	V <sub>CC</sub> - 0.1		V
V <sub>CC</sub> = 4.5\	to 5.5V			,	
ILI	Input Load Current	V <sub>IN</sub> = 0V to V <sub>CC</sub>		±1	μΑ
I <sub>LO</sub>	Output Leakage Current	V <sub>OUT</sub> = 0V to V <sub>CC</sub>		±5	μΑ
I <sub>PP1</sub> <sup>(2)</sup>	V <sub>PP</sub> <sup>(1)</sup> Read/Standby Current	$V_{PP} = V_{CC}$		10	μΑ
	V (1) Otto a allow Commont	$I_{SB1}$ (CMOS), $\overline{CE} = V_{CC} \pm 0.3V$		100	μΑ
I <sub>SB</sub>	V <sub>CC</sub> <sup>(1)</sup> Standby Current	$I_{SB2}$ (TTL), $\overline{CE}$ = 2.0 to $V_{CC}$ + 0.5V		1	mA
I <sub>cc</sub>	V <sub>CC</sub> Active Current	$f = 5 \text{ MHz}, I_{OUT} = 0 \text{ mA}, \overline{CE} = V_{IL}$		25	mA
V <sub>IL</sub>	Input Low Voltage		-0.6	0.8	V
V <sub>IH</sub>	Input High Voltage		2.0	V <sub>CC</sub> + 0.5	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA		0.4	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -400 μA	2.4		V

Notes: 1.  $V_{CC}$  must be applied simultaneously with or before  $V_{PP}$ , and removed simultaneously with or after  $V_{PP}$ .

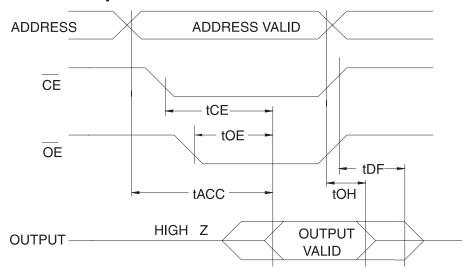
<sup>2.</sup>  $V_{PP}$  may be connected directly to  $V_{CC}$ , except during programming. The supply current would then be the sum of  $I_{CC}$  and  $I_{PP}$ 

#### **AC Characteristics for Read Operation**

 $V_{CC} = 2.7V$  to 3.6V and 4.5V to 5.5V

				AT27BV010					
			-6	90	-12		-15		
Symbol	Parameter	Condition	Min	Max	Min	Max	Min	Max	Units
t <sub>ACC</sub> (3)	Address to Output Delay	$\overline{CE} = \overline{OE} = V_{IL}$		90		120		150	ns
t <sub>CE</sub> <sup>(2)</sup>	CE to Output Delay	OE = V <sub>IL</sub>		90		120		150	ns
t <sub>OE</sub> <sup>(2)(3)</sup>	OE to Output Delay	CE = V <sub>IL</sub>		50		50		60	ns
t <sub>DF</sub> <sup>(4)(5)</sup>	OE or CE High to Output Float, whichever occurred first			40		40		50	ns
t <sub>OH</sub>	Output Hold from Address, $\overline{\text{CE}}$ or $\overline{\text{OE}}$ , whichever occurred first		0		0		0		ns

# **AC Waveforms for Read Operation**(1)

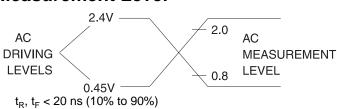


Notes: 1. Timing measurement references are 0.8V and 2.0V. Input AC drive levels are 0.45V and 2.4V, unless otherwise specified.

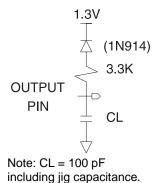
- 2.  $\overline{\text{OE}}$  may be delayed up to  $t_{\text{CE}}$ - $t_{\text{OE}}$  after the falling edge of  $\overline{\text{CE}}$  without impact on  $t_{\text{CE}}$ .
- 3.  $\overline{\text{OE}}$  may be delayed up to  $t_{\text{ACC}}$ - $t_{\text{OE}}$  after the address is valid without impact on  $t_{\text{ACC}}$ .
- 4. This parameter is only sampled and is not 100% tested.
- 5. Output float is defined as the point when data is no longer driven.



# **Input Test Waveform and Measurement Level**



## **Output Test Load**



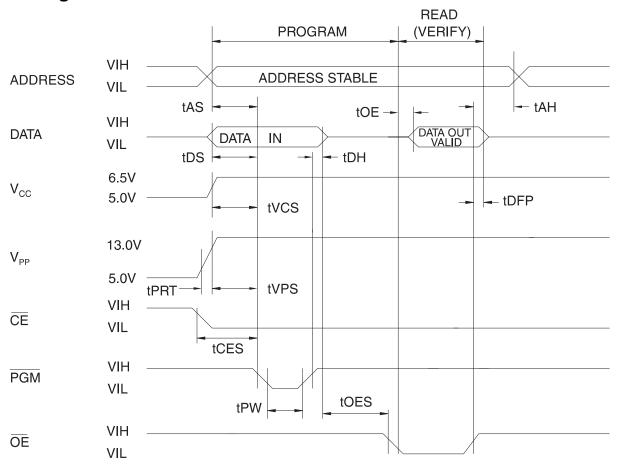
## **Pin Capacitance**

 $f = 1 \text{ MHz}, T = 25^{\circ}C^{(1)}$ 

Symbol	Тур	Max	Units	Conditions
C <sub>IN</sub>	4	8	pF	$V_{IN} = 0V$
C <sub>OUT</sub>	8	12	pF	V <sub>OUT</sub> = 0V

Note: 1. Typical values for nominal supply voltage. This parameter is only sampled and is not 100% tested.

# **Programming Waveforms**<sup>(1)</sup>



- Notes: 1. The Input Timing Reference is 0.8V for  $V_{\rm IL}$  and 2.0V for  $V_{\rm IH}$ .
  - $t_{\text{OE}}$  and  $t_{\text{DFP}}$  are characteristics of the device but must be accommodated by the programmer.
  - When programming the AT27BV010, a 0.1  $\mu$ F capacitor is required across  $V_{PP}$  and ground to suppress spurious voltage transients.

## **DC Programming Characteristics**

 $T_A = 25 \pm 5^{\circ}C, \ V_{CC} = 6.5 \pm 0.25 V, \ V_{PP} = 13.0 \pm 0.25 V$ 

			Lir	Limits	
Symbol	Parameter	Test Conditions	Min	Max	Units
I <sub>LI</sub>	Input Load Current	$V_{IN} = V_{IL}, V_{IH}$		±10	μA
V <sub>IL</sub>	Input Low Level		-0.6	0.8	V
V <sub>IH</sub>	Input High Level		2.0	V <sub>CC</sub> + 1	V
V <sub>OL</sub>	Output Low Voltage	I <sub>OL</sub> = 2.1 mA		0.4	V
V <sub>OH</sub>	Output High Voltage	I <sub>OH</sub> = -400 μA	2.4		V
I <sub>CC2</sub>	V <sub>CC</sub> Supply Current (Program and Verify)			40	mA
I <sub>PP2</sub>	V <sub>PP</sub> Supply Current	$\overline{CE} = \overline{PGM} = V_{IL}$		20	mA
V <sub>ID</sub>	A9 Product Identification Voltage		11.5	12.5	V





## **AC Programming Characteristics**

 $T_A = 25 \pm 5^{\circ}C, \ V_{CC} = 6.5 \pm 0.25V, \ V_{PP} = 13.0 \pm 0.2V$ 

			nits		
Symbol	Parameter	Test Conditions <sup>(1)</sup>	Min	Min Max	
t <sub>AS</sub>	Address Setup Time		2		μs
t <sub>CES</sub>	CE Setup Time		2		μs
t <sub>OES</sub>	OE Setup Time	Input Rise and Fall Times: (10% to 90%) 20 ns	2		μs
t <sub>DS</sub>	Data Setup Time	(10% to 90%) 2011s	2		μs
t <sub>AH</sub>	Address Hold Time	Input Pulse Levels:	0		μs
t <sub>DH</sub>	Data Hold Time	0.45V to 2.4V	2		μs
t <sub>DFP</sub>	OE High to Output Float Delay(2)	Input Timing Reference Level:	0	130	ns
t <sub>VPS</sub>	V <sub>PP</sub> Setup Time	0.8V to 2.0V	2		μs
t <sub>VCS</sub>	V <sub>CC</sub> Setup Time		2		μs
t <sub>PW</sub>	PGM Program Pulse Width <sup>(3)</sup>	Output Timing Reference Level:  0.8V to 2.0V	95	105	μs
t <sub>OE</sub>	Data Valid from OE	0.07 to 2.07		150	ns
t <sub>PRT</sub>	V <sub>PP</sub> Pulse Rise Time During Programming		50		ns

Notes: 1.  $V_{CC}$  must be applied simultaneously or before  $V_{PP}$  and removed simultaneously or after  $V_{PP}$ 

- 2. This parameter is only sampled and is not 100% tested. Output Float is defined as the point where data is no longer driven—see timing diagram.
- 3. Program Pulse width tolerance is 100  $\,\mu\text{sec}\pm5\%.$

# Atmel's 27BV010 Integrated Product Identification Code<sup>(1)</sup>

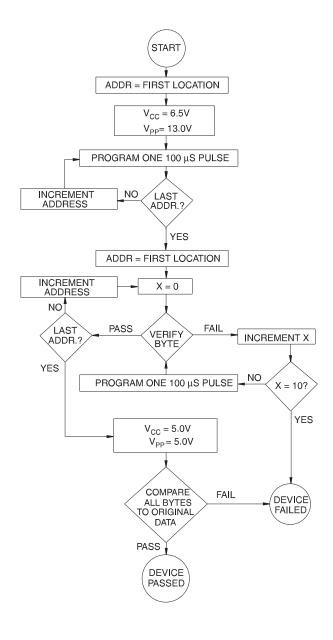
		Pins				Hex				
Codes	Α0	07	O6	<b>O</b> 5	04	О3	O2	01	00	Data
Manufacturer	0	0	0	0	1	1	1	1	0	1E
Device Type	1	0	0	0	0	0	1	0	1	05

Note: 1. The AT27BV010 has the same Product Identification Code as the AT27C010. Both are programming compatible.

#### **Rapid Programming Algorithm**

A 100  $\mu$ s  $\overline{PGM}$  pulse width is used to program. The address is set to the first location.  $V_{CC}$  is raised to 6.5V and  $V_{PP}$  is raised to 13.0V. Each address is first programmed with one 100  $\mu$ s  $\overline{PGM}$  pulse without verification. Then a verification / reprogramming loop is executed for each address. In the event a byte fails to pass verification, up to 10 successive 100  $\mu$ s pulses are applied with a verification

after each pulse. If the byte fails to verify after 10 pulses have been applied, the part is considered failed. After the byte verifies properly, the next address is selected until all have been checked.  $V_{PP}$  is then lowered to 5.0V and  $V_{CC}$  to 5.0V. All bytes are read again and compared with the original data to determine if the device passes or fails.







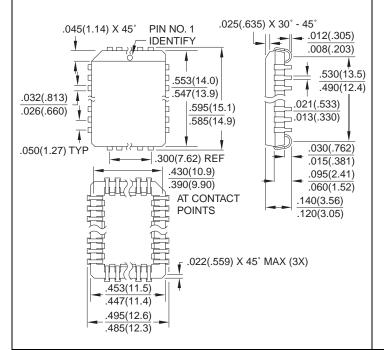
# **Ordering Information**

t <sub>ACC</sub>					
(ns)			Ordering Code	Package	Operation Range
90	8	0.02	AT27BV010-90JC	32J	Commercial
			AT27BV010-90TC	32T	(0°C to 70°C)
			AT27BV010-90VC	32V	
	8	0.02	AT27BV010-90JI	32J	Industrial
			AT27BV010-90TI	32T	(-40°C to 85°C)
			AT27BV010-90VI	32V	
120	8	0.02	AT27BV010-12JC	32J	Commercial
			AT27BV010-12TC	32T	(0°C to 70°C)
			AT27BV010-12VC	32V	
	8	0.02	AT27BV010-12JI	32J	Industrial
			AT27BV010-12TI	32T	(-40°C to 85°C)
			AT27BV010-12VI	32V	
150	8	0.02	AT27BV010-15JC	32J	Commercial
			AT27BV010-15TC	32T	(0°C to 70°C)
			AT27BV010-15VC	32V	
	8	0.02	AT27BV010-15JI	32J	Industrial
			AT27BV010-15TI	32T	(-40°C to 85°C)
			AT27BV010-15VI	32V	

Package Type				
32J	32-Lead, Plastic J-Leaded Chip Carrier (PLCC)			
32T	32-Lead, Plastic Thin Small Outline Package (TSOP) (8 x 20 mm)			
32V	32 Lead, Plastic Thin Small Outline Package (VSOP) (8 x 14 mm)			

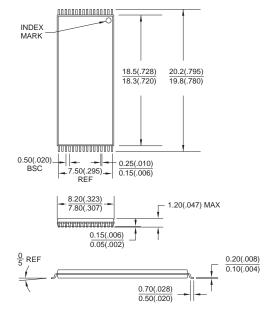
## **Packaging Information**

**32J**, 32-Lead, Plastic J-Leaded Chip Carrier (PLCC) Dimensions in Inches and (Millimeters)
JEDEC STANDARD MS-016 AE



**32T**, 32-Lead, Plastic Thin Small Outline Package (TSOP)

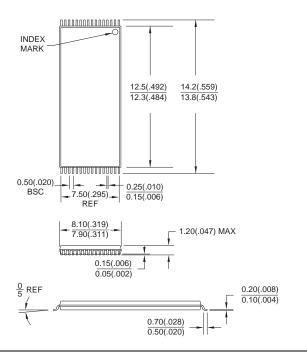
Dimensions in Millimeters and (Inches)\*
JEDEC OUTLINE MO-142 BD



\*Controllling dimension: millimeters

**32V**, 32-Lead, Plastic Thin Small Outline Package (VSOP)

Dimensions in Inches and (Millimeters)
JEDEC OUTLINE MO-142 BA







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